

REMARKS

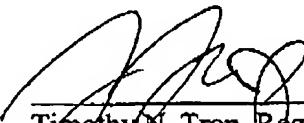
It is conceded that neither Liao or Ciambrone teach an infrared transmissive cap for an integrated circuit. It is suggested that somehow this deficiency is cured by Edwin's teaching of the adverse effects of infrared reflow ovens on printed circuit boards, suggesting that Edwin gives reasons why one would minimize the amount of time a component is exposed to such heat. But, certainly, nothing in Edwin contemplates or suggests in any way the use of an infrared transmissive cap for this purpose.

Moreover, no reference suggests using an infrared transmissive member of any type to reduce the amount of time that a product would be maintained within an oven. The asserted rationale for the combination of producing an integrated circuit that sees one hundred percent of the heat generated by the IR oven is nowhere suggested in the prior art. In other words, the prior art does not tell you that the way to reduce the amount of time a component is exposed to heat is to enable the integrated circuit to see one hundred percent of the heat generated by the IR oven. Moreover, nothing in the prior art suggests that one way to enable the element to see one hundred percent of the heat generated is to use an infrared transmissive cap.

The fact of the matter is that nothing in the prior art suggests any reason to use an infrared transmissive cap in particular. A teaching that it is good to reduce the amount of time of exposure teaches reducing the amount of time of exposure, not the unsuggested concept of using an infrared transmissive cap.

Therefore, reconsideration is respectfully requested.

Respectfully submitted,



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